

Title (en)

SUBSTRATE-MOUNTED CIRCUIT MODULE COMPRISING COMPONENTS IN A PLURALITY OF CONTACT PLANES

Title (de)

SUBSTRAT-SCHALTUNGSMODUL MIT BAUTEILEN IN MEHREREN KONTAKTIERUNGSEBENEN

Title (fr)

MODULE DE CIRCUIT A SUBSTRAT PRESENTANT DES COMPOSANTS DANS PLUSIEURS PLANS DE CONTACT

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2009132922A2] The invention relates to circuit module comprising components that are mounted on a substrate (10). Said substrate (10) comprises a metal carrier layer (20) having a first surface, a first insulating layer (30) directly adjoining the carrier layer (20) being arranged on said first surface. The substrate furthermore comprises a first wiring layer (40) which directly adjoins the first insulating layer (30), which is electroconductive and which is arranged on the first insulating layer (30). The substrate (10) comprises a first contact plane extending along the first surface, at least one of the components being directly electrically connected to the carrier layer (20) in the first contact plane. The invention further relates to a method for producing a circuit module according to the invention, wherein a surface section of the wiring layer (40) and a surface section of the underlying insulating layer (30) are removed and a component is fitted into the recess so produced.

IPC 8 full level

H01L 23/367 (2006.01); **H01L 25/065** (2006.01)

CPC (source: EP US)

H01L 23/142 (2013.01 - EP US); **H01L 23/3677** (2013.01 - EP US); **H01L 24/49** (2013.01 - EP US); **H01L 25/072** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/45015** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48137** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/48472** (2013.01 - EP US); **H01L 2224/49** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01014** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01042** (2013.01 - EP US); **H01L 2924/0105** (2013.01 - EP US); **H01L 2924/01052** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/12041** (2013.01 - EP US); **H01L 2924/1301** (2013.01 - EP US); **H01L 2924/13033** (2013.01 - EP US); **H01L 2924/13034** (2013.01 - EP US); **H01L 2924/13055** (2013.01 - EP US); **H01L 2924/13091** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/19041** (2013.01 - EP US); **H01L 2924/30107** (2013.01 - EP US); **Y10T 29/49162** (2015.01 - EP US)

Citation (search report)

See references of WO 2009132922A2

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